

100V N-Channel MOSFETs

General Description

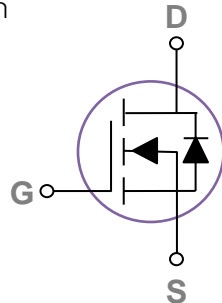
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV_{DSS}	$R_{DS(ON)Max.}$	I_D
100V	4.2mΩ	150A

Features

- 100V, 150A, $R_{DS(ON)Max.} = 4.2m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

TO-263 Pin Configuration



Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ C$)	150	A
	Drain Current – Continuous ($T_c=100^\circ C$)	95	A
I_{DM}	Drain Current – Pulsed ¹	600	A
E_{AS}	Single Pulse Avalanche Energy ²	378	mJ
I_{AS}	Single Pulse Avalanche Current ²	87	A
P_D	Power Dissipation ($T_c=25^\circ C$)	350	W
T_{STG}	Storage Temperature Range	-50 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-50 to 150	$^\circ C$

Note 1: Exceed these limits to damage to the device.

Note 2: Exposure to absolute maximum rating conditions may affect device reliability.

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V , V _{GS} =0V , T _J =25°C			1	uA
		V _{DS} =80V , V _{GS} =0V , T _J =85°C			10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V , V _{DS} =0V			100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =20A		3.5	4.2	mΩ
		V _{GS} =6V , I _D =15A		4.5	6.0	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2.4	2.5	2.75	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient			-8		mV/°C
g _{fs}	Forward Transconductance	V _{DS} =5V , I _D =20A		90		S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{3, 4}	V _{DS} =80V , V _{GS} =10V , I _D =10A		110		nC
Q _{gs}	Gate-Source Charge ^{3, 4}			11.5		
Q _{gd}	Gate-Drain Charge ^{3, 4}			28		
T _{d(on)}	Turn-On Delay Time ^{3, 4}	V _{DD} =50V , V _{GS} =10V , R _G =6Ω I _D =1A		23		ns
T _r	Rise Time ^{3, 4}			32		
T _{d(off)}	Turn-Off Delay Time ^{3, 4}			157		
T _f	Fall Time ^{3, 4}			115		
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz		5218		pF
C _{oss}	Output Capacitance			1223		
C _{rss}	Reverse Transfer Capacitance			62		
R _g	Gate resistance	V _{GS} =0V , V _{DS} =0V , F=1MHz		1.9		Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V , Force Current			150	A
I _{SM}	Pulsed Source Current				300	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25°C			1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=87A., R_G=25Ω, Starting T_J=25°C.
3. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
4. Essentially independent of operating temperature.

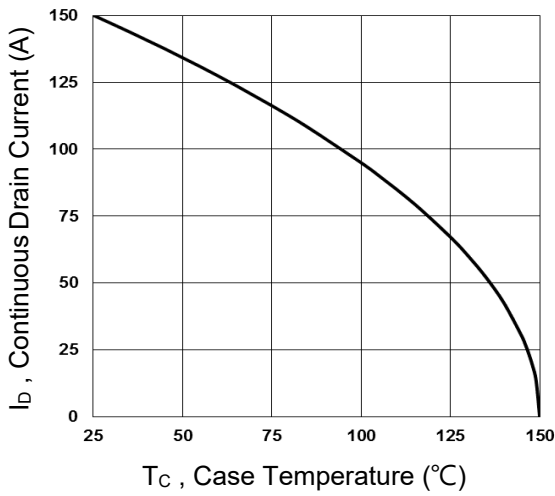


Fig.1 Continuous Drain Current vs. T_c

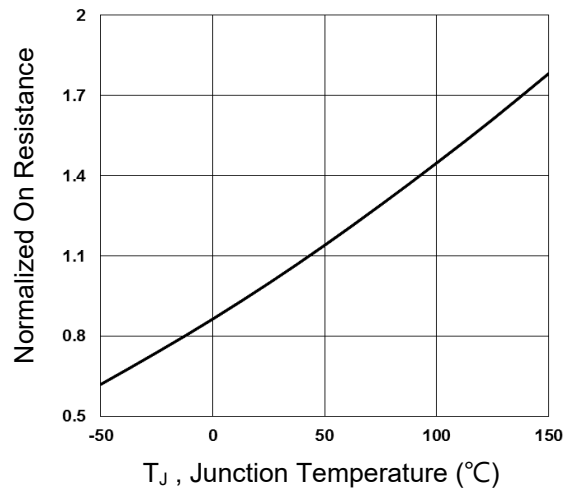


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

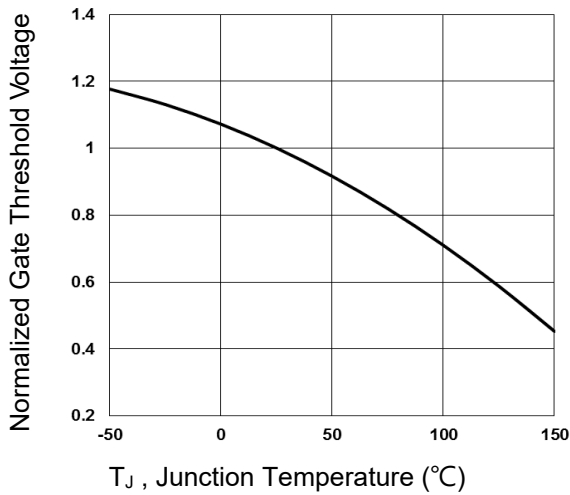


Fig.3 Normalized V_{th} vs. T_j

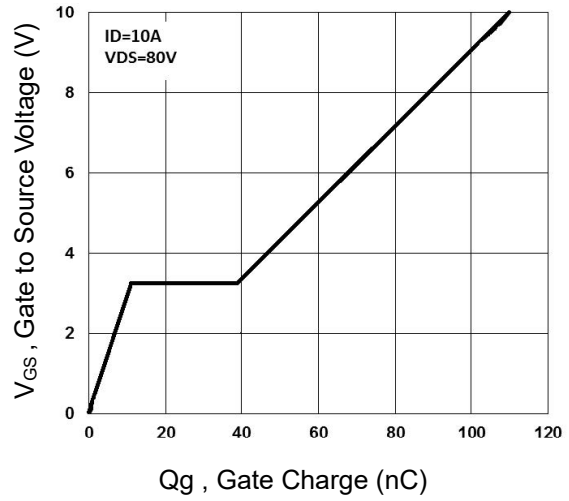


Fig.4 Gate Charge Characteristics

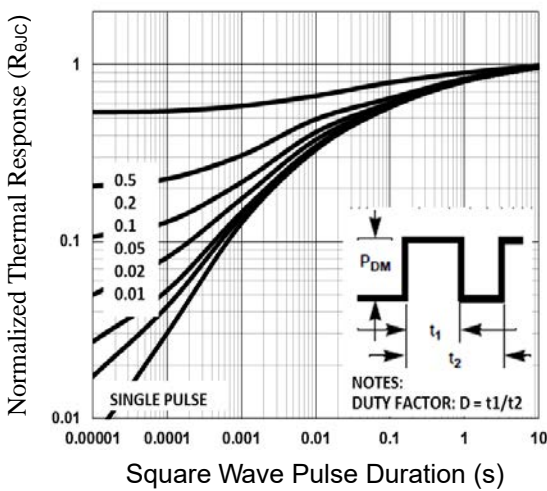


Fig.5 Normalized Transient Impedance

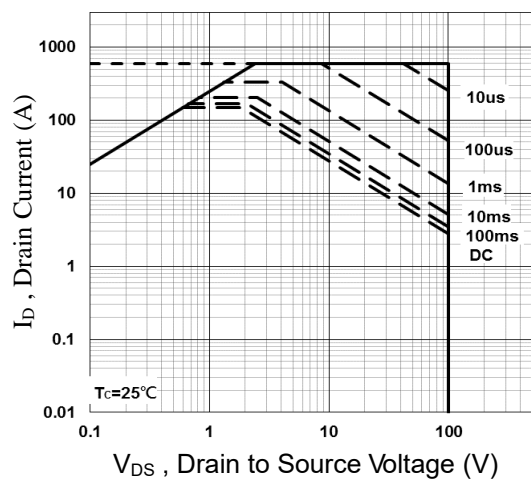


Fig.6 Maximum Safe Operation Area

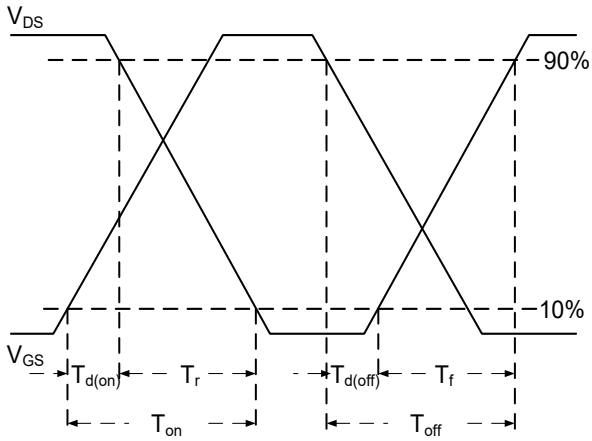


Fig.7 Switching Time Waveform

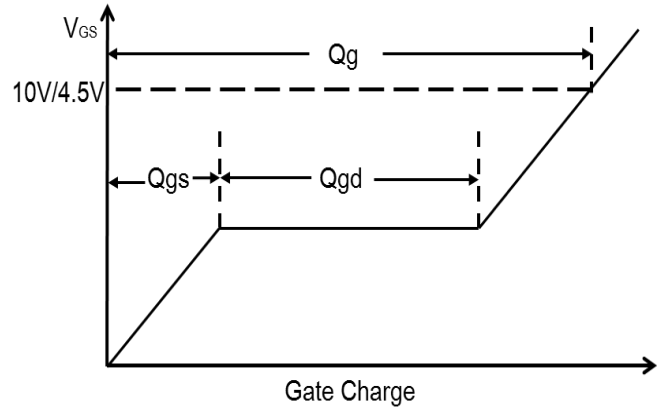


Fig.8 Gate Charge Waveform

TO-263 PACKAGE INFORMATION

